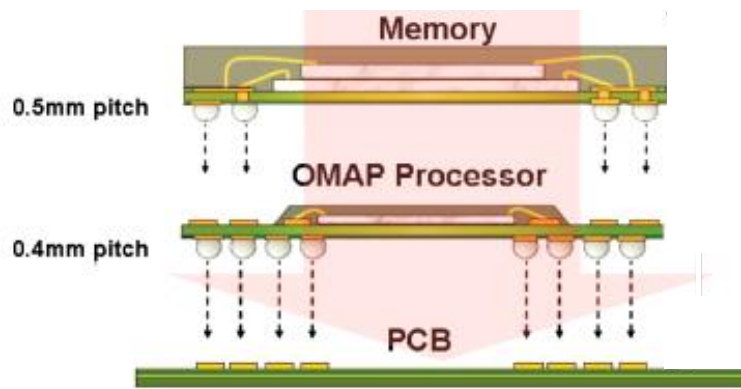


## PACKAGE ON PACKAGE TECHNOLOGY (PoP)

→ Both microprocessor (pitch: 0.4mm) and memory (pitch: 0.5mm) assembled atop each other.



→ Advantages:

- Physical space saved on the PCB.
- Connection between the logic and the memory reduced. As a result, better performance due to the faster signal propagation, reducing noise and cross-talk.
- This technology saves routing of the direction, data and control, therefore the PCB's stack up is easier.
- Compared to others components with the same internal architecture, the memory could be from different manufacturers or features.
- "Puzzle" structure allow the set to be modified. For example: double memory capacity with the same microprocessor.

